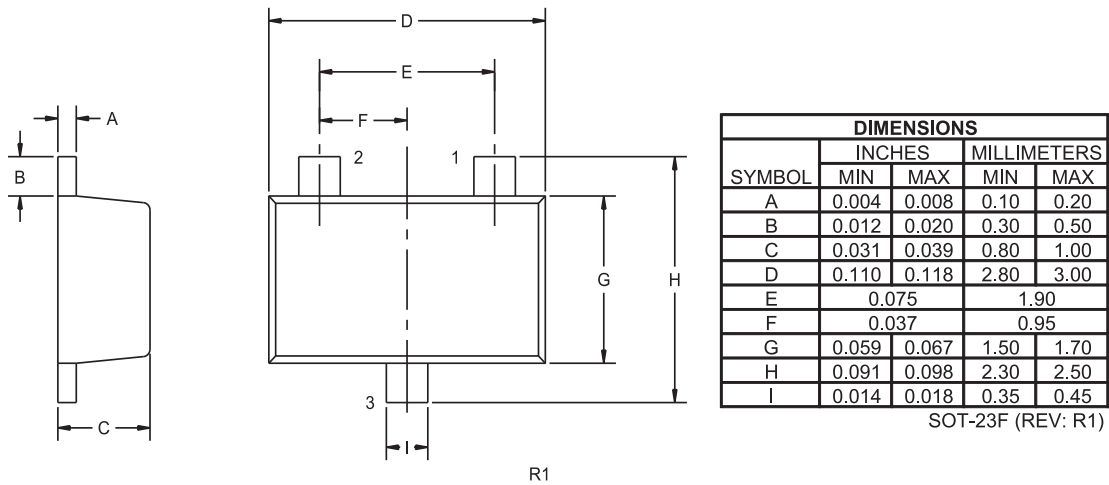


# Package Details

## SOT-23F Case



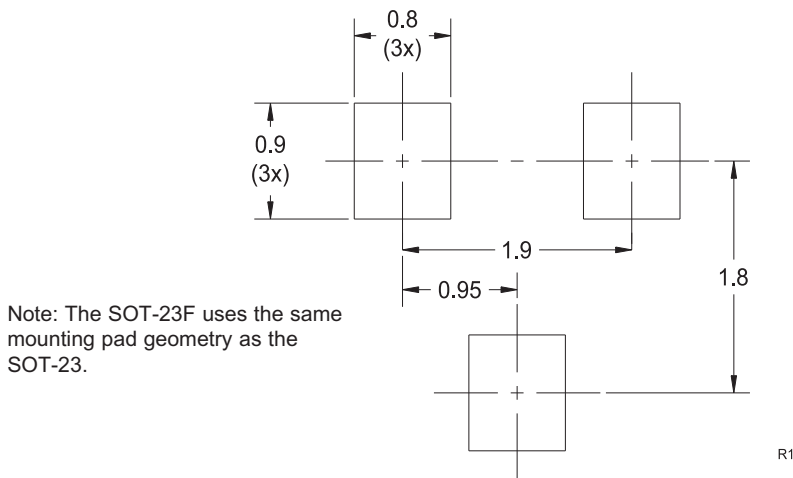
### Mechanical Drawing



**Lead Code:**  
Reference individual device datasheet.

**Part Marking:** 2-4 Character Alpha/Numeric Code

### Mounting Pad Geometry (Dimensions in mm)

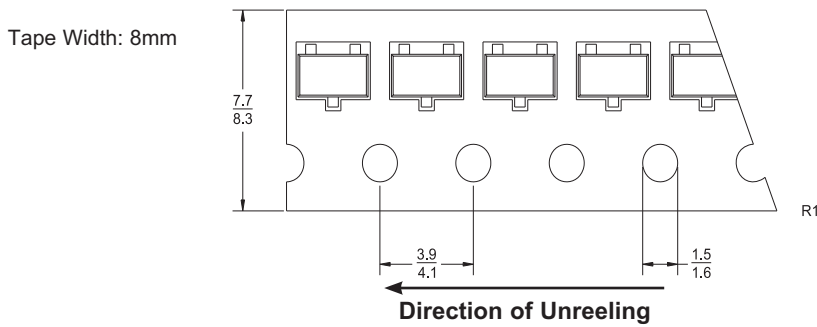


# Package Details

## SOT-23F Case



### Tape Dimensions and Orientation (Dimensions in mm)



\* Devices are taped in accordance with Electronic Industries Association Standard EIA-481-1-A

### Packaging Base

7" Reel = 3,000 pcs.

### Reel Labeling Information

Each reel is labeled with the following information:

Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

### Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7"	9	27,000	9x9x5	23x23x13	4	2
	18	54,000	9x9x9	23x23x23	7	4
	40	120,000	21x9x9	53x23x23	14	7
	108	324,000	27x9x17	69x23x43	39	18

### Ordering Information

- For devices taped and reeled on 7" reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R3 (4-March 2010)

# Material Composition Specification

SOT-23F Case

Pb (lead)-free plating



Device average mass . . . . . 11.0 mg

Fluctuation margin . . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.64%	0.07	Si	7440-21-3	0.64%	0.07	6,364
bond wire	gold	0.2%	0.02	Au	7440-57-5	0.2%	0.022	2,000
leadframe	Cu alloy w/ silver plating	38.38%	4.22	Cu	7440-50-8	37.65%	4.141	376,455
				Fe	7439-89-6	0.04%	0.004	364
				Ag	7440-22-4	0.7%	0.077	7,000
die attach	silver epoxy	0.43%	0.05	Ag	7440-22-4	0.32%	0.035	3,182
				epoxy resin	Proprietary	0.11%	0.012	1,091
encapsulation*	EMC	59.47%	6.54	silica	7631-86-9	42.89%	4.718	428,909
				epoxy resin	Proprietary	14.95%	1.644	149,455
				Sb <sub>2</sub> O <sub>3</sub>	1309-64-4	1.19%	0.131	11,909
				TBBA	79-94-7	0.3%	0.033	3,000
				carbon	1333-86-4	0.15%	0.016	1,455
	EMC GREEN	59.47%	6.54	silica	60676-86-0	39.34%	4.327	393,364
				epoxy resin	37382079-9	6.82%	0.75	68,182
				phenol resin	9003-35-4	6.82%	0.75	68,182
				carbon black	1333-86-4	0.31%	0.034	3,091
				metal hydroxide	1309-42-8	6.19%	0.681	61,909
plating	100% matte tin	0.88%	0.1	Sn	7440-31-5	0.88%	0.097	8,818

\*EMC GREEN molding compound is Halogen-Free.

**Disclaimer**

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R5 (9-March 2010)